

ABSTRACT

A system may include a first integrated circuit die, no-flow underfill material, and a second integrated circuit die. A first side of the first integrated circuit die may include a first plurality of electrical contacts, and the underfill material may contact the first side of the first integrated circuit die. A first side of the second integrated circuit die may include a second plurality of electrical contacts, and the first side of the second integrated circuit die may also contact the no-flow underfill material.